



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUC60N06S5L073	Issued	23. June 2021
MA#	MA005435315		
Package	PG-TDSON-8-33	Weight*	111.37 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.394	0.35	0.35	3538	3538
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		143	
	non noble metal	iron	7439-89-6	0.053	0.05		475	
	non noble metal	copper	7440-50-8	52.842	47.45	47.51	474465	475083
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	399	399
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		691	
	plastics	epoxy resin	-	6.081	5.46		54602	
	inorganic material	silicondioxide	60676-86-0	32.330	29.03	34.56	290292	345585
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14131	14131
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1879	1879
solder	non noble metal	tin	7440-31-5	0.012	0.01		106	
	noble metal	silver	7440-22-4	0.015	0.01		133	
	non noble metal	lead	7439-92-1	0.565	0.51	0.53	5073	5312
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.828	15.11	15.13	151094	151290
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2779	2783
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com